



LOW CONTACT RESISTANCE

SELF-CLEANING CONTACTS

HIGH RELIABILITY

Standard Dip Switches

SPECIFICATIONS

MECHANICAL

Mechanical life: 2000 operations per switch. Operation force: 400gf max. (12 series).

1000gf max. (10 & 11 series).

Stroke: 2.0mm.

Operation temp: -20 °C to 70 °C. Storage temp: -40 °C to 85 °C.

Vibration test: MIL-STD-202F method 201A. Dielectric strength: 500VAC/1 minute.

Frequency: 10-55-10Hz/1 min. Directions: X, Y, Z, three mutually

perpendicular directions. Time: 2 hours each direction.

High reliability.

Shock test: MIL-STD-202F method 213B. Condition A.

Gravity: 50G (peak value),11 m/sec. Direction and times: 6 sides and 3 times in

each direction. High reliability.

ELECTRICAL

Electrical life: 2000 operations per switch 24VDC, 25mA.

Non-switching rating: 100mA, 50VDC. Switching rating: 25mA, 24VDC. Contact resistance: $50m\Omega$ max. at initial.

Insulation resistance: (at 500VDC) $100M\Omega$ min.

Capacitance: 5pF max.

Circuit: single pole single throw.

Marking: special side or top marking optional.

MATERIALS

Base: UL94V-0 PBT thermoplastic, black. Cover: UL94V-0 PBT thermoplastic, red, black,

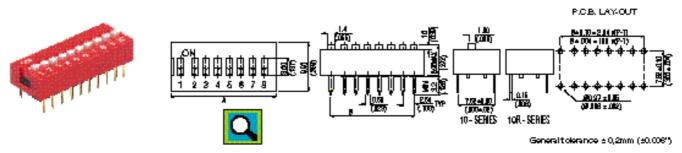
blue.

Actuators: UL94V-0 PBT thermoplastic, white. Contact: phosphor bronze with gold plating

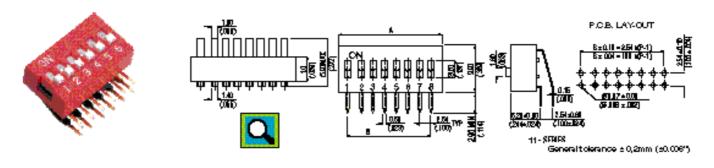
over nickel.

Top seal: polyester film. Potting material: epoxy.

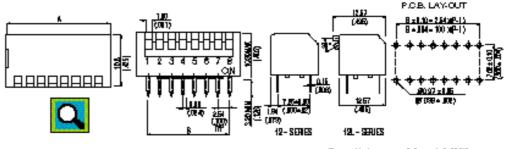
MODEL 10



MODEL 11







General tolerance ± 0,2mm (±0,006*)

SWITCHES









Standard Dip Switches

SOLDERING AND CLEANING PROCESSES

For best results, please follow these recommendations:

Keep all switch contacts in their "OFF" position adhere to the switch. for all operations.

Wave soldering: recommended solder temperature at 500 F (260 °C) max. 5 seconds. Hand soldering: use a soldering iron of 30 Watts or less, controlled at 608 °F (320 °C) approximately 2 seconds while applying solder. Cleaning process: flux clean using force rinse, high agitation or triple bath cleaning method. Freon TF or TE give excellent results. When vapor methods are used, do not subject the switch to solvents at temperature above 125 °F (51 °C).

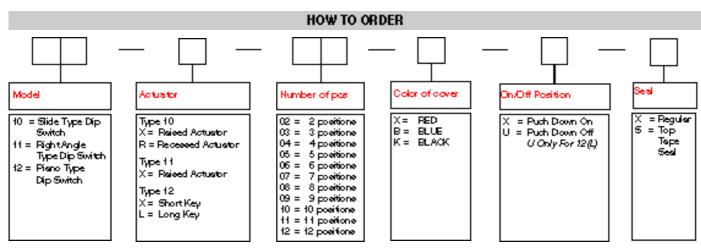
Care should be exercised so that flux from the upper part of the printed circuit board does not

Do not clean the switch body except with top tape sealed type, which can only spray of cleaning method from top s/w.

DIMENSIONS

MOR			BO. OF POS.	DIMLA 12,121	DBLA 10,108,11
10 -12 10R-12	11-12	12 -12 12L-12	12	32.04 (1.261)	31.84 (1.254)
10 -10 10R-10	11-10	12 -10 12L-10	10	26.96 (1.061)	26.76 (1.054)
10 -09 10R-09	11-09	12 -09 12L-09	9	24.42 (961)	24.22 (954)
10 -08 10R-08	11-08	12 -08 12L-08	8	21.88 (861)	21.68 (854)
10 -07 10R-07	11-07	12 -07 12L-07	7	19:34 (.761)	19.14 (.754)
10 -06 10R-06	11-06	12 -06 12L-06	6	16.80 (.661)	16.60 (654)
10 -05 10R-05	11-05	12 -05 12L-05	5	1426 (561)	14.06 (554)
10 -04 10R-04	11-04	12 -04 12L-04	4	11.72 (.461)	11.52 (.454)
10 -03 10R-03	11-03	12 -03 12L-03	3	9.48 (361)	8.98 (354)
10 -02 10R-02	11-02	12 -02 12L-02	2	6.64 (261)	6.44 (254)

BCHEMATIC(TYPE)



Specifications are subject to change without notice

